

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT3979273

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
TETSUYA ARAI	07/26/2016
SHUICHI TSUKADA	07/26/2016
JUNKI TANIGUCHI	07/26/2016
RECEIVING PARTY DATA	
Name:	MICRON TECHNOLOGY, INC.
Street Address:	8000 SOUTH FEDERAL WAY
City:	BOISE
State/Country:	IDAHO
Postal Code:	83716
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15220310
CORRESPONDENCE DATA	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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Email:	ip.docket.se@dorsey.com
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ATTORNEY DOCKET NUMBER:	P260505.US.01
NAME OF SUBMITTER:	MIKA ITO
SIGNATURE:	/Mika Ito/
DATE SIGNED:	07/26/2016
Total Attachments: 3	
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Tetsuya Arai, Shuichi Tsukada, and
Junki Taniguchi

Filed: Concurrently herewith

For: SEMICONDUCTOR DEVICE
INCLUDING BUFFER CIRCUIT

Docket No. P260505.US.01

Disclosure No. 2016-0042.00/US

ASSIGNMENT:

Enclosed for recording

Previously recorded

Date:

Reel:

FOR GOOD AND VALUABLE CONSIDERATION, the receipt, sufficiency and adequacy of which are hereby acknowledged, the undersigned do hereby:

SELL, ASSIGN AND TRANSFER to Micron Technology, Inc. (the "Assignee"), a corporation of Delaware, having a place of business at 8000 South Federal Way, Boise, Idaho 83716-9632, the entire right, title and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned concurrently herewith and is entitled "SEMICONDUCTOR DEVICE INCLUDING BUFFER CIRCUIT"; such application and all divisional, continuing, substitute, renewal, reissue and all other applications for patent which have been or shall be filed in the United States and all foreign countries on any of such improvements; all original and reissued patents which have been or shall be issued in the United States and all foreign countries on such improvements; and specifically including the right to file foreign applications under the provisions of any convention or treaty and claim priority based on such application in the United States of America;

AUTHORIZE AND REQUEST the issuing authority to issue any and all United States and foreign patents granted on such improvements to the Assignee;

WARRANT AND COVENANT that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to

others by the undersigned, and that the full right to convey the same as herein expressed is possessed by the undersigned;

COVENANT that, when requested and at the expense of the Assignee, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all such improvements; execute all rightful oaths, declarations, assignments, powers of attorney and other papers; communicate to the Assignee all facts known to the undersigned relating to such improvements and the history thereof; and generally do everything possible which the Assignee shall consider desirable for securing, maintaining and enforcing proper patent protection for such improvements and for vesting title to such improvements in the Assignee;

TO BE BINDING on the heirs, assigns, representatives and successors of the undersigned and extend to the successors, assigns and nominees of the Assignee.

Signature: Tetsuya Arai

Date: 2016-7-26
(YYYY-MM-DD)

Assignor Name: Tetsuya Arai

Witness 1:

Signature: Shoko Tomita

Date: 2016-7-26
(YYYY-MM-DD)

Witness Name: Shoko Tomita

Witness 2:

Signature: Miku Takemasa

Date: 2016-7-26
(YYYY-MM-DD)

Witness Name: Miku Takemasa

Docket No. P260505.US.01

Signature: Shuichi Tsukada

Date: 2016-7-26
(YYYY-MM-DD)

Assignor Name: Shuichi Tsukada

Witness 1:	
Signature: <u>Shoko Tomita</u>	Date: <u>2016-7-26</u> (YYYY-MM-DD)
Witness Name: Shoko Tomita	
Witness 2:	
Signature: <u>Miku Takemasa</u>	Date: <u>2016-7-26</u> (YYYY-MM-DD)
Witness Name: Miku Takemasa	

Signature: Junki Taniguchi

Date: 2016-7-26
(YYYY-MM-DD)

Assignor Name: Junki Taniguchi

Witness 1:	
Signature: <u>Shoko Tomita</u>	Date: <u>2016-7-26</u> (YYYY-MM-DD)
Witness Name: Shoko Tomita	
Witness 2:	
Signature: <u>Miku Takemasa</u>	Date: <u>2016-7-26</u> (YYYY-MM-DD)
Witness Name: Miku Takemasa	